

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. .... 10/039,456  
Priority Filing Date ..... December 31, 2001  
 Inventor ..... Ying Huang et al.  
 Assignee ..... Micron Technology, Inc.  
Priority Group Art Unit ..... 2829  
Priority Examiner ..... S.B. Geyer  
 Attorney's Docket No. .... MI22-2347  
 Title: An Improved Method, Structure and Process Flow to Reduce Line-Line Capacitance  
 with Low-K Material

**INFORMATION DISCLOSURE STATEMENT**

References - - See attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a continuation application of co-pending application Serial No. 10/039,456, filed December 31, 2001, upon which the above-identified application relies for a priority date under 35 U.S.C. §120. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. §1.98(d) and MPEP §609(2).

Citation of these references is respectfully requested.

Respectfully submitted,

Date: 7-23-03



D. Brent Kenady  
 Reg. No. 40,045

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| Form PTO-1449                                                       |  | U.S. DEPARTMENT OF COMMERCE<br>PATENT AND TRADEMARK OFFICE |  |  | ATTY. DOCKET NO.<br>M122-2347  |  | Priority SERIAL NO.<br>10/039,456 |  |
| LIST OF ART CITED BY APPLICANT<br>(Use several sheets if necessary) |  |                                                            |  |  | APPLICANT<br>Ying Huang et al. |  |                                   |  |
|                                                                     |  |                                                            |  |  | FILING DATE                    |  | GROUP                             |  |

  

| U.S. PATENT DOCUMENTS |    |                 |          |                |       |          |                            |
|-----------------------|----|-----------------|----------|----------------|-------|----------|----------------------------|
| *Examiner Initial     |    | Document Number | Date     | Name           | Class | Subclass | Filing Date If Appropriate |
|                       | AA | 5,946,601       | 8/99     | Wong et al.    |       |          |                            |
|                       | AB | 6,033,979       | 3/00     | Endo           |       |          |                            |
|                       | AC | 6,037,664       | 3/00     | Zhao et al.    |       |          |                            |
|                       | AD | 6,046,104       | 4/00     | Kepler         |       |          |                            |
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|                       | AG | 5,122,483       | 06/92    | Sakai et al.   |       |          |                            |
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|                       | AK |                 |          |                |       |          |                            |
|                       | AL |                 |          |                |       |          |                            |

  

| FOREIGN PATENT DOCUMENTS |    |                 |      |         |       |          |             |    |
|--------------------------|----|-----------------|------|---------|-------|----------|-------------|----|
|                          |    | Document Number | Date | Country | Class | Subclass | Translation |    |
|                          |    |                 |      |         |       |          | Yes         | No |
|                          | AM |                 |      |         |       |          |             |    |
|                          | AN |                 |      |         |       |          |             |    |
|                          | AO |                 |      |         |       |          |             |    |
|                          | AP |                 |      |         |       |          |             |    |
|                          | AQ |                 |      |         |       |          |             |    |

  

| OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.) |    |                                                                                                                        |
|-------------------------------------------------------------------------|----|------------------------------------------------------------------------------------------------------------------------|
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|                                                                         | AS | Singer, Peter, "Dual-Damascene Challenges Dielectric-Etch," Semiconductor International August 1999, pp. 1-5           |
|                                                                         | AT |                                                                                                                        |

  

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| EXAMINER | DATE CONSIDERED |
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.